

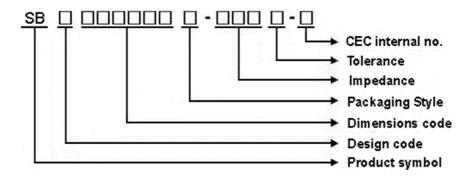
ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

Halogen Free & RoHs Compliance

SPECIFICATION FOR APPROVAL

| CUSTOMER: | Eltech | | | |
|--|----------|--|------------------|--|
| CUSTOMER P/N: | | | | |
| OUR DWG No: | | | | |
| QUANTITY: | 0 | Pcs. | DATE: | 2014/07/02 |
| ITEM: | | SBJ | 060303T- | Series-N |
| | | | | |
| | _ | PECIFICA | _ | |
| COMPONENT | | | | |
| ENGINEER | | | | |
| ELECTRICAL | | | | |
| ENGINEER | | | | |
| MECHANICAL | | | | |
| ENGINEER | | | | |
| APPROVED | | | | |
| REJECTED | | | | |
| 奇力新電子股份有限公司 Chilisin Electronic sCorp No. 29, Alley 301, Tehhsin Rd Hukou, Hsinchu 303, Taiwan TEL: +886-3-599-2646 FAX: +886-3-599-9176 E-mail: sales@chilisin.com.tw http://www.chilisin.com.tw | , | Chilis No. 7 Qing: TEL FAX | 8, Puxing Rd., \ | Dongguan) Co., Ltd. Yuliangwei Administration Area, uan City, Guangdong,China -0251~3 3-0232 |
| 奇力新電子(河南)有限公 Chilisin Electronics (Henan) Co XiuWu Xian, industry gathering JiaoZuo, Henan China Postal Code:454350 TEL:+86-391-717-0666 FAX:+86-391-717-0666 | o., Ltd. | Chilis No.14 Suzh Posta TEL: FAX: | | Suzhou) Co., Ltd. Rd., Suzhou New District, 350 356 |
| DRAWN BY 趙燕玲 annie | 謝 | CHECKED 鼎文 kevin | | APPROVED BY 詹嘉皓 allen.chan |

- 1 Scope: This specification applies to MULTILAYER FERRITE CHIP BEADS
- 2 Part Numbering: Product Identification



3 Rating:

Operating Temperature: $-5.5 \, ^{\circ} \text{C} \sim 1.2.5 \, ^{\circ} \text{C}$ (Including self - temperature rise)

Storage Temperature: $-5.5\% \sim 1.2.5\%$ (after PCB)

4 Marking:

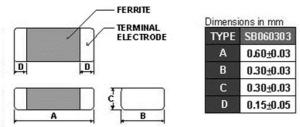
No Marking

5 Standard Testing Condition

| | Unless otherwise specified | In case of doubt |
|-------------|----------------------------------|------------------|
| Temperature | Ordinary Temperature(15 to 35°ℂ) | 20±2 ℃ |
| Humidity | Ordinary Humidity(25 to 85% RH) | 60 to 70 % RH |



6 Configuration and Dimensions:



7 ELECTRICAL CHARACTERISTICS :

| Part No. | Impedance (Ω) | Test Freq. | RDC (Ω)Max. | Rated Current (mA)Max. |
|-------------------|------------------|----------------|----------------|------------------------------|
| SBJ060303T-600□-N | 60 | 100 MHz,200 mV | 0.3 | 200 |
| SBJ060303T-750□-N | 75 | 100 MHz,200 mV | 0.4 | 300 |

NOTE: -tolerance Y=±25% / T=±30%

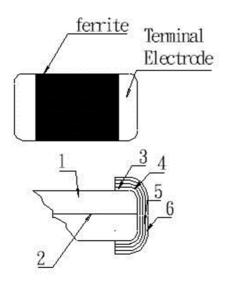
^{1.}Operating temperature range - 5 $^{\circ}\text{C} \sim 1$ 2 $5\,^{\circ}\text{C}$ (Including self - temperature rise)

[&]quot;-N" FOR COMPLETELY LEAD FREE TYPE(INCLUDING FERRITE BODY & SOLDER)



8 SBJ060303T Series

8.1 Construction:



8.2 Material List:

| NO | PART | MATERIAL |
|--------------|-------------------|---------------------|
| 1 | Ferrite Substance | NiO-CuO-ZnO-Ferrite |
| 2 | Silver electrode | Ag |
| 3 | Silver electrode | Ag |
| 4 Cu plating | | Cu |
| 5 | Ni plating | Ni |
| 6 | Sn plating | Sn |

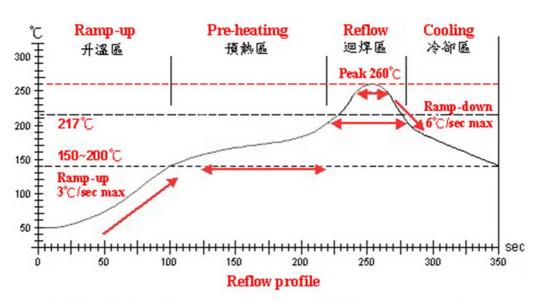


9 Reliability Of Ferrite Multilayer Chip Bead 1-1.Mechanical Performance

| No | Item | Specification | Test Method |
|-------|------------------------------|---------------------------------|---|
| 1-1-1 | Flexure Strength | The forces applied on the right | Test device shall be soldered on the substrate |
| | | conditions must not damage | Substrate Dimension: 100x40x1.6mm |
| | | the terminal electrode and the | Deflection: 2.0mm |
| | | ferrite | Keeping Time: 30sec |
| | | | *For 100505, substrate dimension is 100x40x0.8mm |
| 1-1-2 | Vibration | | Test device shall be soldered on the substrate |
| | | | Oscillation Frequency: 10 to 55 to 10Hz for 1min |
| | | | Amplitude: 1.5mm |
| | | | Time: 2hrs for each axis (X, Y & Z), total 6hrs |
| 1-1-3 | Resistance to Soldering Heat | Appearance: No damage | Pre-heating: 150°ℂ, 1min |
| | | More than 75% of the terminal | Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) |
| | | electrode should be covered | Solder Temperature: 260±5℃ |
| | | with solder. | Immersion Time: 10±1sec |
| | | Impedance: within ±30% of | |
| | | initial value | |
| 1-1-4 | Solder ability | The electrodes shall be at | Pre-heating: 150℃, 1min |
| | | least 95% covered with new | Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) |
| | | solder coating | Solder Temperature: 245±5°C (Pb-Free) |
| | | | Immersion Time: 4±1sec |
| | | | |
| 1-1-5 | Terminal Strength Test | No split termination | Test device shall be soldered on the substrate, |
| | | Chip | then apply a force in the direction of the arrow. |
| | | F | Force : 2N |
| | | | Keeping Time: 10±1sec |
| | | Mounting Pad | |

| No | Item | Specification | Test Method | | | |
|--|------------------------|--------------------------|--|------------------|------------|--|
| 1-2-1 | Temperature Cycle | Appearance: No damage | One cycle: | | | |
| | | Impedance: within±30% of | Step | Temperature (°ℂ) | Time (min) | |
| | | initial value | 1 | -55±3 | 30 | |
| | | | 2 | 25±2 | 3 | |
| | | | 3 | 125±3 | 30 | |
| | | | 4 | 25±2 | 3 | |
| | | | Total: 100cycles | | | |
| | | | ndition for 24hrs | | | |
| 1-2-2 | Humidity Resistance | | | | | |
| | | | Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for | | | |
| | | | | | | |
| 1-2-3 | High | | Temperature: 125±3°C / Relative Humidity: 0% | | | |
| | Temperature Resistance | | Applied Current: Rated Current /Time: 1000hrs | | | |
| | | | Measured after exposure in the room condition for 24h | | | |
| 1-2-4 | Low | | Temperature: -55±3°C | | | |
| Temperature Resistance Relative Humidity: 0% / | | | umidity: 0% / Time: 1000hrs | | | |
| | | | Measured after exposure in the room condition for 2 | | | |





Lead-Free(LF) 標準溫度分析範圍

Refer to J-STD-020C

| 管制項目 Item. | 升溫區 Ramp-up | 預熱區 Pre-heatimg | 迴焊區 Reflow | Peak Temp | 冷部區 Cooling |
|---------------------|----------------|--------------------|---------------|-------------|--------------------|
| 温度範圍 Temp.scope | R.T. ~150°C | 150℃ ~ 200℃ | 217℃ | 260±5°C | Peak Temp. ~ 150°C |
| 標準時間 Time spec. | _ | 60 ~ 180 sec | 60 ~ 150 sec | 20 ~ 40 sec | _ |
| 實際時間 Time result | _ | 75 ~ 100 sec | 90 ~ 120 sec | 20 ~ 35 sec | _ |

NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow



11 PACKAGING

11.1 Packaging -Cover tape

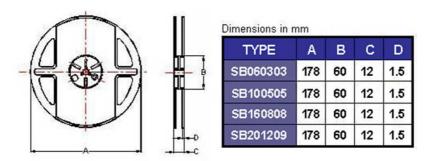
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

| TYPE | BULK | PCS/REEL |
|----------|----------|----------|
| SB060303 | ✓ | 15000 |
| SB100505 | ✓ | 10000 |
| SB160808 | 1 | 4000 |
| SB201209 | * | 4000 |

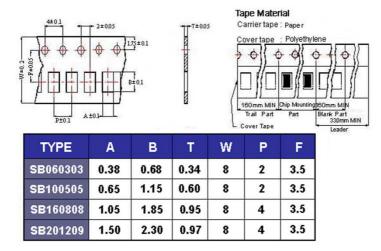
11.3 Reel Dimensions



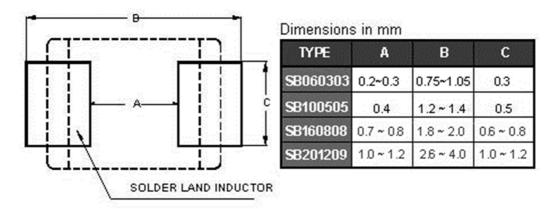


11 PACKAGING

11.4 Tape Dimensions in mm



12 Recommended Pattern



13 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)